

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1460lhs8-2.5#trpbf

(Engineering Calculation)

SOT-23

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**TOTAL MASS (g) : 0.013164**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000481	1000000	36538.46875		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu [HD]	Copper (Cu)	7440-50-8	0.003510	975000	266632.0625		
		Iron (Fe)	7439-89-6	0.000083	23000	6304.97460938		
		Phosphorus (P)	7723-14-0	0.000001	400	75.9635543823		
		Zinc (Zn)	7440-66-6	0.000006	1600	455.781311035		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.003600</b>	<b>1000000</b>	<b>273468.75</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000227	1000000	17259.5253906		
		<b>External Plating Total:</b>				<b>0.000227</b>	<b>1000000</b>	<b>17259.5253906</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000036	1000000	2734.68798828		
<b>Internal Plating Total:</b>				<b>0.000036</b>	<b>1000000</b>	<b>2734.68798828</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000281	750000	21345.7578125		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000094	250000	7140.57421875		
<b>Die Attach Total:</b>				<b>0.000375</b>	<b>1000000</b>	<b>28486.3320312</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000488	58000	37070.2109375		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.007485	890000	568587.1875		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000421	50000	31980.65625		
		Carbon Black (C)	1333-86-4	0.000017	2000	1291.38037109		
		<b>Encapsulation Total:</b>				<b>0.008411</b>	<b>1000000</b>	<b>638929.375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000034	1000000	2582.76074219		
					<b>TOTAL MASS (g) :</b>	<b>0.013164</b>		